Delivering pervasive semiconductors for humankind
Disclaimer

This presentation and the accompanying oral presentation include "forward-looking statements," that reflect our current expectations and views of future events. These forward-looking statements are made under the "safe harbor" provisions of the U.S. Private Securities Litigation Reform Act of 1995 and include but are not limited to, statements regarding our financial outlook, future guidance, product development, business strategy and plans, and market trends, opportunities and positioning. These statements are based on current expectations, assumptions, estimates, forecasts, projections and limited information available at the time they are made. Words such as "expect," "anticipate," "should," "believe," "hope," "target," "project," "goals," "estimate," "potential," "predict," "may," "will," "might," "could," "intend," "shall," "outlook," "on track," and variations of these terms or the negative of these terms and similar expressions are intended to identify these forward-looking statements, although not all forward-looking statements contain these identifying words. Forward-looking statements are subject to a broad variety of risks and uncertainties both known and unknown. Any inaccuracy in our assumptions and estimates could affect the realization of the expectations or forecasts in these forward-looking statements. For example, our business could be impacted by the COVID-19 pandemic and supply chain disruptions due to the Russia/Ukraine conflict and actions taken in response to such events; the market for our products may develop more slowly than expected or than it has in the past; our operating results may fluctuate more than expected; there may be significant fluctuations in our results of operations and cash flows related to our revenue recognition or otherwise; a network or data security incident that allows unauthorized access to our network or data or our customers’ data could damage our reputation; we could experience interruptions or performance problems associated with our technology, including a service outage; and global economic conditions could deteriorate. It is not possible for us to predict all risks, nor can we assess the impact of all factors on our business or the extent to which any factor, or combination of factors, may cause actual results or outcomes to differ materially from those contained in any forward-looking statements we may make. Moreover, we operate in a competitive and rapidly changing market, and new risks may emerge from time to time. You should not rely upon forward-looking statements as predictions of future events. These statements are based on our historical performance and on our current plans, estimates and projections in light of information currently available to us, and therefore you should not place undue reliance on them.

Although we believe that the expectations reflected in our statements are reasonable, we cannot guarantee that the future results, levels of activity, performance or events and circumstances described in the forward-looking statements will be achieved or occur. Moreover, neither we, nor any other person, assumes responsibility for the accuracy and completeness of these statements. Recipients are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date such statements are made and should not be construed as statements of fact. Except to the extent required by federal securities laws, we undertake no obligation to update any information or any forward-looking statements as a result of new information, subsequent events, or any other circumstances after the date hereof, or to reflect the occurrence of unanticipated events.

This presentation and the accompanying oral presentation also contain estimates and other statistical data made by independent parties and by us relating to market size and growth and other data about our industry and business. This data involves a number of assumptions and limitations, and you are cautioned not to give undue weight to such estimates. We have not independently verified the industry data generated by independent parties and contained in this presentation and, accordingly, we cannot guarantee their accuracy or completeness. In addition, projections, assumptions, and estimates of our future performance and the future performance of the markets in which we compete are necessarily subject to a high degree of uncertainty and risk.

In addition to the financial information presented in accordance with International Financial Reporting Standards ("IFRS"), this presentation includes the following adjusted non-IFRS metrics: adjusted gross profit (loss), adjusted gross margin, adjusted net income (loss), adjusted diluted earnings (loss) per share and adjusted EBITDA. We define adjusted gross profit (loss) as gross profit (loss) adjusted for share-based compensation expense. We define adjusted gross margin as adjusted gross profit (loss), which is gross profit (loss) before share-based compensation, divided by net revenues. We define adjusted EBITDA as adjusted net income (loss), excluding the impact of finance expense, income tax expense, depreciation, amortization, share-based compensation expense, transaction gains and associated expenses, restructuring charges and litigation settlements. We define adjusted EBITDA margin as adjusted EBITDA divided by net revenues.

We believe that in addition to our results determined in accordance with IFRS, these adjusted non-IFRS measures provide useful information to both management and investors in measuring our financial performance and highlight trends in our business that may not otherwise be apparent when relying solely on IFRS measures. These adjusted non-IFRS financial measures provide supplemental information regarding our operating performance that excludes certain gains, losses and non-cash charges that occur relatively infrequently and/or that we consider to be unrelated to our core operations. For further information regarding these non-IFRS measures, please refer to "Appendix" in this presentation.

Adjusted non-IFRS financial information is presented for supplemental informational purposes only and should not be considered in isolation or as a substitute for financial information presented in accordance with IFRS. Our presentation of adjusted non-IFRS measures should not be construed as an inference that our future results will be unaffected by unusual or nonrecurring items. Other companies in our industry may calculate these measures differently, which may limit their usefulness as a comparative measure.
Delivering a new era of more innovation more impact
GF at a glance

$6.6B
2021 revenue

2.4M
2021 wafer shipments (300mm eq.)

>200
customers in 2021

5
manufacturing sites across three continents

~15,000
employees

~10,000
patents

10.28.21
GFS Nasdaq listed
GF journey

Creation
GlobalFoundries was created based on the thesis that the world needed a geographically diverse alternative to Taiwan.

Transformation
Strategically re-positioned to serve pervasive semiconductor end markets
- Strengthened management team aligned to mission
- Refocused investments & accelerated differentiated solutions focused on pervasive markets
- Increased single-sourced products
- Driving margin expansion and earnings growth

Realization
The world’s leading manufacturer of feature-rich semiconductor solutions
- Gain share in secular end-markets
- Innovate in purpose-built platforms and solutions
- Capital efficient expansion through partnerships
- Deliver best-in-class financials

2009 2017 2018 2021 2022 2030
Delivering solutions to customers around the globe

10 Countries and time zones
11 Service languages
<10 km Median proximity to top customers

- Automotive
- Communications Infrastructure and Datacenter
- Home and Industrial IoT
- Smart Mobile Devices
- Compute
- GF Field Site
Purpose-built customer engagements

**Certainty**
- ~80%
  - 2022-2025 capacity covered by LTAs

**Durability**
- 90%
  - single-sourced DWINs\(^{(1)}\)
  - in 1H’22

**Profitability**
- \(\uparrow 19\%\)
  - YoY mix and pricing increase 1H’21 - 1H’22\(^{(2)}\)

**Multi-year Capacity Coverage**

Note:
1. A DWIN, or design win, is defined as the successful completion of the evaluation stage, where a customer has assessed our technology solution, verified that it meets its requirements, qualified it for their products and confirmed to us their selection.
2. Wafer hardware only
GF’s ecosystem: more than a decade in the making

### Design enablement network

<table>
<thead>
<tr>
<th>IP</th>
<th>FDX™</th>
<th>RF</th>
<th>EDA</th>
<th>Design services</th>
<th>OSAT</th>
</tr>
</thead>
</table>

### Our partner community

- **100+**
  Ecosystem partners spanning IP, EDA, OSAT and design services

- **4500+**
  Total IP titles across all nodes from >50 IP partners

- **950+**
  IP titles currently in active development across 26 process nodes and 34 IP partners

- **300+**
  Clients enabled by ecosystem partner IPs in the last 5 years

- **1700+**
  Client designs enabled by ecosystem partners in the last 5 years
End-markets and Solutions
Technology megatrends shaping the global economy

- Smart, connected devices
- Adoption of AR & VR
- Explosion of AI & ML
- Data everywhere

Megatrends accelerated or limited by semiconductors
Foundries are essential to global GDP

Market Size (2021)

$89T
Global GDP

$2.2T
Electronics

$595B
Semiconductors
~6% CAGR growth (21-26)

$96B
Foundry
~6% CAGR growth (21-26)

1,000s of companies

100s of companies

Only 5 at scale\(^1\), 3 of which are in China and Taiwan

Semiconductors outpace GDP & foundry outpaces semiconductors

Source: Global GDP: World Bank, IMF. Electronics; Semiconductors and Foundry: Gartner *Forecast, Semiconductor Foundry Revenue, Supply and Demand, Worldwide, 1Q22 Update (April 2022)

Note:
1. Excludes smaller foundry players, defined as those with less than $2Bn of foundry revenue
Uniquely positioned in markets that matter

Smart Mobile Devices

Home and Industrial IoT

Automotive

Communications Infrastructure & Datacenter

2020 SAM $23B
2030 SAM $40B
2020 SAM $16B
2030 SAM $32B
2020 SAM $4B
2030 SAM $14B
2020 SAM $10B
2030 SAM $25B
Smart Mobile Devices

**4G LTE/5G: RF**
- RF FE Sub-6GHz
- RF SOI
- Higher Data Rate
- Power Efficiency

**5G: RF FE**
- mmWave
- FDX™
- Expanded Range
- Power Efficiency

**4G LTE/5G: Transceiver**
- FinFET
- Higher Data Rate
- Power Efficiency

**Wi-Fi: Wi-Fi 6/6E**
- FinFET
- Higher Data Rate
- Power Efficiency

**Camera: Optical Imaging**
- Feature-Rich CMOS
- Sensor Fusion
- Power Efficiency

**Smart Audio**
- Feature-Rich CMOS (BCD, eNVM)
- Audio Quality
- Haptic Response

**Secure Payment: NFC**
- Feature-Rich CMOS (eNVM)
- Integration of NFC+ Secure Element
- Secure Manufacturing

**Touch Screen: Display**
- Feature-Rich CMOS
- Functional Integration
- Power Efficiency

**Power Management: RF, Audio**
- Feature-Rich CMOS (BCDLite®), FDX™
- Increased Efficiency
- Smaller Form Factor

GF has 75% of silicon area in top premier smartphones in RF FE, Audio & NFC
Home and Industrial IoT

**Smart Camera:**
Image Sensing
- FDX™
- Edge Intelligence
- Low Power Connectivity

**Smart Features: SoC**
- Feature-Rich CMOS
- High Transfer Rate
- Power Efficiency
- Edge Intelligence

**Smart Control: WL MCU**
- FDX™
- Power
- Wireless (BLE, Wi-Fi, 15.4)

**Smart Features: MCU**
- Feature-Rich CMOS (BCD)
- Power Management

**Secure Transactions/Interactions: NFC**
- Feature-Rich CMOS (eNVM)
- Power Efficiency

**Smart Speaker:**
Audio
- Feature-Rich CMOS (BCD, eNVM)
- Power Efficiency
- Power Management

**Wi-Fi Connection:**
- Wi-Fi
- FDX™
- Edge Intelligence
- Low Power Connectivity

**Touch Screen:**
- Display
- Feature-Rich CMOS
- Sensor Fusion
- Power Efficiency

**Medical IoT:**
Medical Sensing
- FDX™
- Edge Intelligence
- Low Power Connectivity
Automotive

5G Connection:
RF FEM mmWave
FDX™
RF mmWave
Low Power Connectivity

Vehicle Power:
DC-DC, BMS, Charger
Feature-Rich CMOS (BCD, eNVM)
High Voltage
Precision
Power Efficiency
Power Management

Vehicle Network:
Zone/Domain/Fusion
Controllers
FDX™, FinFET
Power Efficiency
High Performance
High Temperature

Comfort/Customization/
Keyless Entry: MCU,
NFC, BLE, UWB
Feature-Rich CMOS (eNVM)
Power Efficiency
Edge Intelligence

ADAS: Radar
FDX™
RF mmWave
Power Efficiency
Edge Intelligence

Touch Screen: Display
Feature-Rich CMOS
Sensor Fusion
Power Efficiency

ADAS: LiDAR
Silicon Photonics
High Transfer Rate
Power Efficiency
Edge Intelligence

User Experience:
IVI, Cluster
Feature-Rich CMOS (BCD)
Power Efficiency
Power Management
Communications Infrastructure & Datacenter

5G Infrastructure:
RF FEM mmWave
RF SOI, SiGe, 22FDX®
RF mmWave
Power efficiency

5G Infrastructure:
Network processor / Switch
FinFET, Feature-Rich CMOS
Performance analog/mixed signal

Data communications:
Redriver
SiGe
Signal loss compensation
Data reliability & integrity

4G LTE/5G Infrastructure: RF FEM Sub-6GHz
RF SOI, SiGe
RF features
Power efficiency

Connectivity:
Optical networking
Silicon Photonics
Data throughput >4x Cu
Cu replacement for inter and intra DC connectivity

Chiplets/2.5D/3D: IOD
FinFET
Performance analog/mixed signal

Novel compute:
AI/Photonics/Quantum
FinFET, Silicon Photonics
System integration: electronics & photonics
Highest performance/power efficiency

Power delivery
Feature-rich CMOS (BCDLite®)
High Voltage
High efficiency
GF is everywhere
Global Footprint
Manufacturing at a glance

99%
line yield up to 15 years reliability

>31M
hours worked in 2020 at better than safety benchmarks

5
manufacturing sites across three continents

800 NPIs
per year, ramped in 6-9 months to HVM

99%
on time delivery

Zero
stock outs impacting customer commitments
Global manufacturing footprint & strategy

- Malta, NY, USA
- Burlington, VT, USA
- Dresden, Germany
- Crolles, France
- Singapore
- East Fishkill, NY, USA*

*Transfer to Onsemi end of 2022

Supply chain security through dual-technology qualification

Economies of scale through modular expansion at existing sites

Capital efficiency through partnership model

+50% Capacity increase by 2020 vs 2025
## Global manufacturing footprint - current

<table>
<thead>
<tr>
<th>Location</th>
<th>Capacity</th>
<th>Technology</th>
</tr>
</thead>
<tbody>
<tr>
<td>Malta, NY, USA 300mm</td>
<td>400 kwpa</td>
<td>FinFET, NVM, RFSOI, SiPh</td>
</tr>
<tr>
<td>Singapore 300mm &amp; 200mm</td>
<td>730 &amp; 370 kwpa</td>
<td>BCD/BCDLite, HV, NVM, DDI, RFSOI, LP SiGe</td>
</tr>
<tr>
<td>Dresden, Germany 300mm</td>
<td>680 kwpa</td>
<td>FDX™, NVM, HV, BCDLite</td>
</tr>
<tr>
<td>Burlington, VT, USA 200mm</td>
<td>250 kwpa</td>
<td>RFSOI, SiGe, GaN</td>
</tr>
<tr>
<td>East Fishkill, NY, USA 300mm</td>
<td>150 kwpa</td>
<td>HP CMOS, RFSOI</td>
</tr>
</tbody>
</table>

### Notes:
1. Kwpa is defined as 2022 capacity in thousand wafers per annum
2. 200mm capacity translated to 300mm equivalent
Capacity expansion roadmap

Roadmap

1. 2022 space at full utilization of current capacity
2. Full build-out within 4 walls
3. Under construction

Notes:
1. 200mm capacity translated to 300mm equivalent, in kwpa.
2. Full build up Plan through 2028.
3. Does not include future capacity plans under development

Global manufacturing FOOTPRINT focused on supply security, diversity & sustainability

- >50% capacity expansion from 2020 levels
- Economy of scale through modular expansion at existing sites in global footprint
- Dual site sourcing provides flexibility & security
- 25% GHG reduction in emissions by 2030
Global manufacturing footprint – beyond ‘23

- **Malta, NY, USA**
  - **Capacity:** 570 kwpa
  - **Technology:** FinFET, NVM, RFSOI, SiPh
  - **300mm**

- **Singapore**
  - **Capacity:** 1,200 kwpa & 370 kwpa
  - **Technology:** BCD/BCDLite, HV, NVM, DDI, RFSOI, LP SiGe
  - **300mm & 200mm**

- **Dresden, Germany**
  - **Capacity:** 850 kwpa
  - **Technology:** FDX™, NVM, HV, BCDLite
  - **300mm**

- **Burlington, VT, USA**
  - **Capacity:** 280 kwpa
  - **Technology:** RFSOI, SiGe, GaN
  - **200mm**

- **Crolles, France**
  - **Capacity:** 360 kwpa
  - **Technology:** 22FDX®
  - **300mm**

**Note:**
1. Kwpa is defined as 2022 capacity in thousand wafers per annum
2. 200mm capacity translated to 300mm equivalent
Crolles, France partnership with STMicroelectronics

GF co-managed facility

- On site GF management supplemented by Dresden expertise
- Direct oversight of all planning and operations
- Depreciation, fixed and variable cost sharing model based on actual utilization and consumption
- Stable and low-cost energy supply through French Nuclear energy network

Phase 0: Install 20 unique FDX™ tools to form pilot line for technology transfer starting 2023

Phase 1-3: Ramp starts Q4’24. Full build up to 360kwp
Singapore modular expansion

First tool-in announced in June 2022
Ready for production in 2023
>1.5M of 300mm equivalent wafers serving Auto, Mobile and IoT
Secured government grants and customer commitments
Malta, NY expansion

Expansion announced in July 2021

Planning and preliminary permitting underway

Strong government and customer partnerships

CHIPS and Science Act signed into law in August 2022
Sustainable operations

Journey to ZERO Carbon

2015-2021

- **38%** Reduction in electricity use intensity
- **36%** Reduction in GHG emissions intensity
- **40%** Reduction in water use intensity
- **62,100** Tons annualized reduction of chemical use and waste

2022 and Beyond

- **33%** Reduction in electricity use intensity by 2025
- **25%** Absolute reduction in GHG emissions by 2030 (1)
- **33%** Reduction in water use intensity by 2025
- **90%** Landfill avoidance in 2022

Note:
1. GHG emissions include scope 1 and 2
Technology Development
Technology Development at a glance

~1400 technologists in dedicated research teams

>30K wafers per year dedicated to development

>50 universities, government partners and other research institutes partnered in collaborative efforts

>150 differentiated programs built on 25+ world class platforms
Innovation through market-driven purpose-built platforms

Optimizing digital processing & application specific features

- Feature-Rich CMOS: Complementary Metal-Oxide Semiconductor
- FinFET: Fin Field-Effect Transistor
- Mixed-technologies for power management, high-voltage, embedded memory
- High performance, power efficient “Systems-On-a-Chip”

The ultimate in low power, performance with superior connectivity

- FDX: Fully-Depleted SOI
- Enabling new high-performance, low-power applications
- RF SOI: RF Silicon-on-Insulator
- Low power / low noise / low latency / high frequencies
- SiPh: Silicon Photonics
- Higher data rates with greater power efficiency
- SiGe: Silicon Germanium
- Power amplifier and very-high-frequency applications

Innovating beyond silicon

- WBG: GaN: Gallium Nitride
- High efficiency power conversion

Innovation beyond transistor size
How we innovate: Smart Mobile Device
Ultra-fast, seamless, reliable connectivity

End user applications
Bridging the cellular and wireless experience effortlessly

Capabilities required
- Rate
- Range
- Power

GF’s differentiated performance
- RF SOI
- FDX™
- SiGe
- GaN
## Investing for a bold future

<table>
<thead>
<tr>
<th>Feature-Rich CMOS</th>
<th>FinFET</th>
<th>FDX™ FD-SOI</th>
<th>RF SOI</th>
<th>SiPh</th>
<th>SiGe</th>
<th>GaN/Si (WBG)</th>
</tr>
</thead>
<tbody>
<tr>
<td>130nm BCD Lite® Gen1 BCD Lite® Gen2 BCD Auto BCD+ NVM BCD+ 120V 55nm BCD Lite® eNVM BCD IVR SPAD/BSI Auto 40nm Auto ISP DDI/HV eNVM mmW 28nm ISP DDI/HV eNVM BCD Lite® µLED</td>
<td></td>
<td>12LP Auto RF IC 12LP+ ULP</td>
<td>22FDX ULL/ULP RF/mmW MRAM Auto</td>
<td>180nm TSW LNA SW PA NSX NSX-Gen2</td>
<td>90nm 90WG 250um pitch Fiber Array attach High Power Wave Guides</td>
<td>130nm Power Amp 9HP+ Power Amp TSV 9HP Power Amp 9HP+ 45S01 Power Amp 40LP-SiGe</td>
</tr>
</tbody>
</table>

### Huge features portfolio:
120 technology solutions enabling thousands of customer products

### 2022 expansion:
+ 16 technology solutions
+ 6 new platforms
+ dozens of new features in dev.

### Beyond Si solutions:
Adding wide bandgap materials for power and RF – GaN/Si
Physical sciences innovation
- Materials enabling new capabilities
- New devices to extend and expand applications
- Advanced tooling and processes

Design innovation
- System level architecture explorations
- Heterogeneous integration
- AI-enabled design
- Circuit topologies

Partnership / ecosystem
- Expanded university engagements
- Customer collaborative projects
- Government supported and targeted R&D
- Lab-to-lab

Market Focus
- 6G and beyond
- AR / VR
- Datacenter
- Quantum computing
- Automotive
GF Labs: Our R&D ecosystem of partners

**University Partnerships**

- Princeton University
- UC Riverside
- UC San Diego
- KU Leuven
- The Ohio State University
- Rice University
- Georgia Institute of Technology
- UCI Samuels Institute of Computing Science
- Rensselaer
- Nanotechnology University
- University of California, Santa Barbara
- Purdue University
- University of Massachusetts Amherst
- Texas Tech University
- Lund University
- Technische Universität Dresden
- University of Calgary
- University of Twente

**Government Partnerships**

- DARPA
- European Commission
- EDB Singapore

**Consortia / R&D Institutes**

- IMEC
- SRC (Semiconductor Research Corporation)
- CMC Microsystems
- Leti (Laboratoires d'Electronique et de Microtechnique de Grenoble)
- Fraunhofer
- IME (Institute of Microelectronics)
- PowerAmerica
- ASIC (American Semiconductor Industry Coalition)
Environmental, Social Governance
Commitment to ESG

Environmental

Journey to Zero Carbon: 25% Greenhouse Gas (GHG) emissions reduction by 2030

>36K annualized metric tons of Carbon equivalent savings achieved in 2019 / 2020

>415K annualized cubic meters water savings achieved in 2019 / 2020

Social

13 total GF Awards in 2019, 2020 and 2021 for exceptional performance in CSR and EHS

200 / 200: Perfect scores in 2020-2021 Responsible Business Alliance audits

World Class: GF TRIR 2020 safety rate (0.13) lowest in our history

GF named one of “America’s Safest Companies” in 2020*

Governance

4 independent Board directors

Independent audit, risk, and compliance committee

Experienced global compliance function

Enterprise risk management framework

Conflict-free supply chain for 3TG: gold, tantalum, tungsten and tin

Source: EHS Today*
GFShield: a foundation of trust

Beneficial geopolitical landscape
During times of increasing international trade conflicts, GF benefits from the resilience of global scale of operations in stable low-risk geographies (United States, Germany and Singapore)

Pedigree of secure at-scale manufacturing
1. Only pure-play foundry in The United States Department of Defense Trusted Foundry Program
2. ISO 15408 Certification to manufacture Common Criteria Secure Products
3. ISO 27001 Certification for Information Security Management

Intellectual Property (IP) protection
With an industry-leading track record protecting GF IP and customers' IP

In a world of escalating threats and risks in the technology sector, our foundation of trust offers a strong competitive edge
Supply chain responsibility, resiliency and security

"Completed the RBA validated audit process achieving PLATINUM status with a full audit score of 200/200"  
RBA Recognition, Fab 9

100% of 3TG minerals we use are conflict free

Stable and Diverse Geographic Footprint

Trusted Supplier to DoD
Critical Supplier - Defense Production Act
Our Team and Culture
Our global team

~15,000 employees

~10,500 employees working in STEM fields

~75% employees with university degrees (PhD, masters, bachelors)

>90 nationalities in 13 countries

~80% engineers, technicians and operators

>1000 new college graduates hired 2018 – present

~25% female workforce

~10,500 employees working in STEM fields
GF senior leadership team

Dr. Thomas Caulfield  
CEO & President

David Reeder  
Chief Financial Officer

Juan Cordovez  
Chief Commercial Officer

Mike Hogan  
Chief Business Officer

Gregg Bartlett  
Chief Technology Officer

KC Ang  
Chief Manufacturing Officer

Mike Cadigan  
Chief Quality Officer

Kevin Soukup  
Chief Strategy Officer

Pradheepa Raman  
Chief People Officer

Laurie Kelly  
Chief Communications Officer

Saam Azar  
General Counsel
GF board of directors

Ahmed Yahia  
Chairman of the Board

Dr. Thomas Caulfield

Tim Breen

Ahmed Saeed Al Calily

Glenda Dorchak  
Independent

Martin L. Edelman

David Kerko  
Independent

Jack Lazar  
Independent

Elissa Murphy  
Independent

Carlos Obeid

Bobby Yerramilli-Rao  
Independent
Investing in our team and communities

1.4M
hours invested in training our employees in 2020

>4300
GlobalGives employee members

$1.2M
donated in 2021, includes employee donations with corporate funding

>2500
Employee resource group members worldwide

- GlobalWomen
- BRAG (Black Resource Affinity Group)
- GlobalFamilies
- VRG (Veterans Resource Group)
- Early Career and Tenure Resource Group
- Unidos, Hispanic/Latinx Resource Group
- ASIA (Asian Society for Inclusion and Awareness), AAPI Resource Group
- Pride@GF, LGBTQ+ Resource Group
Our Mission

We innovate and partner with our customers to deliver technology solutions for humanity.

We manufacture semiconductors around the globe.

Our Vision

We are changing the industry that is changing the world.
Our Values

Create
- Innovate beyond what is possible today
- Differentiate our technology to enable customer success
- Have a passion for problem-solving
- Create value for our customers and for our shareholders

Partner
- Collaborate across all borders & boundaries
- Strive for win-win outcomes
- Build trust as the basis of every relationship

Embrace
- Diversity is a competitive advantage
- The best ideas come from being inclusive
- Act with a shared sense of purpose
- Respect everyone

Deliver
- Our customers can count on us to deliver on our commitment
- Work effectively, efficiently and decisively
- Focus on outcomes and are accountable for results
- Celebrate and reward success
- Nothing matters without safety

All with unyielding integrity
Links

GF.com
News & Events
GF Investor Relations Website
GF Leadership Team
GF Board of Directors
Diversity & Inclusion
Environmental Social Governance at GF
Careers at GF
Connect with GF

GlobalFoundries
@GlobalFoundries
GlobalFoundries
GlobalFoundries.Corporate
Appendix
The making of a global semiconductor manufacturer

GF formed by a joint venture between Mubadala and AMD

Acquired Chartered Semiconductor

Fabricated 1 in Dresden reached $2B revenue

Acquired IBM Microelectronics

Acquired Samsung partnership on 14nm manufacturing

Launched FDX™ platform

- 14nm technology reached $1B revenue
- Ramped Fab 8, Malta NY


- Tom Caulfield named CEO
- 22FDX® surpassed $2B customer design wins
- Strategic reposition to feature-rich solutions

- Carved out and sold ASIC business
- Optimized at-scale global manufacturing footprint
- Delivered more than $1B 8SW customer design wins

- Moved HQ to New York
- Broke ground on new fab in Singapore
- Announced major auto collaborations
- Fab 8 expansion announced
- GF IPO

- Shipped record number of wafers
- Zero operational disruptions
- GF Shield launched

- Delivered more than 22FDX® sales
- GF IPO
How we innovate: Industrial & Home IoT

End user applications
- Smart home appliances
  - Smart speaker
  - Security system

Capabilities required
- Intuitive
- Pain-free
- Efficient
- Convenient
- Trusted

GF's differentiated performance
- FDX®
- Feature rich
- CMOS
- BCD
- NVM
How we innovate: next gen 5G infrastructure

End user applications

- Increased range + greater area coverage
- Increased data rate + low latency for HD video and AR/VR

Capabilities required

- 5G sub 8GHz / mmWave
- Satellite Communications
- Reliability / availability

GF’s differentiated performance

- SiGe
- Feature-rich CMOS
- FDX®
How we innovate: Smart Mobile Device

Hyperconnected human experience bridging physical & digital worlds

End user applications

Capabilities required

- Touch
- Hear
- See
- Trust

GF’s differentiated performance

- FDX®
- BCDL®
- NVM
- HV
How we innovate: Industrial & Home IoT

**End user applications**
- Video streaming
- Connected camera
- Smart home

**Capabilities required**
- Rate
- Range
- Battery life

**GF’s differentiated performance**
- FDX®
How we innovate: ADAS

End user applications

Autopilot in highway and urban traffic scenarios

Capabilities required

- Range
- Field of view
- Resolution
- Robustness
- Power
- Intelligence

GF’s differentiated performance

FDX®
SiGe Feature-rich CMOS
FinFET
How we innovate: Automotive

End user applications

300+ mile range
Delivering a smartphone like user experience
Time to charge

Capabilities required

Efficient power:

- Creation
- Conversion
- Monitoring

GF’s differentiated performance

BCD
Feature-rich CMOS
GaN
Manufacturing operations leadership

KC Ang
Chief Manufacturing Officer

Peter Benyon
SVP and GM Malta, NY Fab

Joseph Chia
VP and GM GIGA+ Singapore Fab

Manfred Horstmann
SVP and GM European Fabs

Pradip Singh
SVP & GM, Global Manufacturing Operations Excellence

Zhimin Gu
VP, New Singapore Fab Operations

Ken McAvey
VP and GM Burlington, VT Fab

Neil Perullo
VP and GM East Fishkill, NY Fab

Yew Kong Tan
SVP and GM Singapore Fabs